
**Neposredno ogrevani termistorji z negativnim temperaturnim koeficientom - 2. del:
Področna specifikacija - Termistorji z negativnim temperaturnim koeficientom za
površinsko montažo - Dopolnilo A1 (IEC 60539-2:2003/A1:2010)**

Directly heated negative temperature coefficient thermistors - Part 2: Sectional
specification - Surface mount negative temperature coefficient thermistors (IEC 60539-
2:2003/A1:2010)

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Direkt geheizte temperaturabhängige Widerstände mit negativem
Temperaturkoeffizienten - Teil 2: Rahmenspezifikation - Oberflächenmontierbare
temperaturabhängige Widerstände mit negativem Temperaturkoeffizienten (IEC 60539-
2:2003/A1:2010)

[SIST EN 60539-2:2004/A1:2010](https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-cf8ef4841306/sist-en-60539-2-2004-a1-2010)

[https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-
cf8ef4841306/sist-en-60539-2-2004-a1-2010](https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-cf8ef4841306/sist-en-60539-2-2004-a1-2010)

Thermistors à coefficient de température négatif à chauffage direct - Partie 2:
Spécification intermédiaire - Montage en surface de thermistors à coefficient de
température négatif (CEI 60539-2:2003/A1:2010)

Ta slovenski standard je istoveten z: EN 60539-2:2004/A1:2010

ICS:

31.040.30 Termistorji Thermistors

SIST EN 60539-2:2004/A1:2010 en

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[SIST EN 60539-2:2004/A1:2010](https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-cf8ef4841306/sist-en-60539-2-2004-a1-2010)

<https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-cf8ef4841306/sist-en-60539-2-2004-a1-2010>

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60539-2/A1

September 2010

ICS 31.040.30

English version

**Directly heated negative temperature coefficient thermistors -
Part 2: Sectional specification -
Surface mount negative temperature coefficient thermistors
(IEC 60539-2:2003/A1:2010)**

Thermistors à coefficient de température
négatif à chauffage direct -
Partie 2: Spécification intermédiaire -
Montage en surface de thermistors
à coefficient de température négatif
(CEI 60539-2:2003/A1:2010)

Direkt geheizte temperaturabhängige
Widerstände mit negativem
Temperaturkoeffizienten -
Teil 2: Rahmenspezifikation -
Oberflächenmontierbare
temperaturabhängige Widerstände
mit negativem Temperaturkoeffizienten
(IEC 60539-2:2003/A1:2010)

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[SIST EN 60539-2:2004/A1:2010](https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-c1c474110054/iec-60539-2-2003-a1-2010)

[https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-](https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-c1c474110054/iec-60539-2-2003-a1-2010)

This amendment A1 modifies the European Standard EN 60539-2:2004; it was approved by CENELEC on 2010-09-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this amendment the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This amendment exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 40/2034/CDV, future amendment 1 to IEC 60539-2:2003, prepared by IEC TC 40, Capacitors and resistors for electronic equipment, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as amendment A1 to EN 60539-2:2004 on 2010-09-01.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

- latest date by which the amendment has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2011-06-01
- latest date by which the national standards conflicting with the amendment have to be withdrawn (dow) 2013-09-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of amendment 1:2010 to the International Standard IEC 60539-2:2003 was approved by CENELEC as an amendment to the European Standard without any modification.

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[SIST EN 60539-2:2004/A1:2010](https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-cf8ef4841306/sist-en-60539-2-2004-a1-2010)

<https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-cf8ef4841306/sist-en-60539-2-2004-a1-2010>

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
<i>Replace the reference:</i>				
IEC 60068-2-58	1999	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	1999
<i>with the following:</i>				
IEC 60068-2-58	2004	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58 + corr. December	2004 2004

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IEC 60539-2

Edition 1.0 2010-07

INTERNATIONAL STANDARD

NORME INTERNATIONALE

AMENDMENT 1
AMENDEMENT 1

**Directly heated negative temperature coefficient thermistors –
Part 2: Sectional specification – Surface mount negative temperature coefficient
thermistors**

**Thermistances à coefficient de température négatif à chauffage direct –
Partie 2: Spécification intermédiaire – Thermistances à coefficient de
température négatif pour montage en surface**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

PRICE CODE
CODE PRIX

C

ICS 31.040.30

ISBN 978-2-88912-045-1

FOREWORD

This amendment has been prepared by IEC technical committee 40: *Capacitors and resistors for electronic equipment*.

The text of this amendment is based on the following documents:

CDV	Report on voting
40/2034/CDV	40/2051/RVC

Full information on the voting for the approval of this amendment can be found in the report on voting indicated in the above table.

The committee has decided that the contents of this amendment and the base publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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[SIST EN 60539-2:2004/A1:2010](https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-cf8ef4841306/sist-en-60539-2-2004-a1-2010)

1.2 Normative references

<https://standards.iteh.ai/catalog/standards/sist/9ba1ab9b-4255-42bb-abf0-cf8ef4841306/sist-en-60539-2-2004-a1-2010>

Modify the reference to IEC 60068-2-58:1999 as follows:

IEC 60068-2-58:2004, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

4.6.2 Test conditions

4.6.2.1 Solder bath method

Replace the text of Subclause 4.6.2.1 by the following new text:

See IEC 60068-2-58, Clauses 6 and 8, if not otherwise specified in the detail specification.

4.6.2.2 Infrared and forced gas convection soldering system

Replace the title and the text of Subclause 4.6.2.2 by the following new title and text:

4.6.2.2 Reflow method

See IEC 60068-2-58, Clauses 7 and 8, if not otherwise specified in the detail specification.

4.7.1 Test conditions

4.7.1.1 Solder bath method

Replace the text of Subclause 4.7.1.1 by the following new text: